



(Green) PLCC Package RELIABILITY QUALIFICATION REPORT SUMMARY

Technology Description	Green (Lead and Halide Free) Plastic Leaded Chip Carrier, J-bend / 4 sides lead shape, 28, 32, 44 & 68 pin counts
Qualification Vehicles	PLCC28 PLCC32 PLCC68

<u>PLCC Package Information</u>	
UL flammability class	UL 94 V-0 & $\geq 28\%$
Lead Frame Material	Copper
Die Attach	Ablestik 8361J
Mold compound	Sumitomo EME-G600T
Bond Wire	Gold
Lead Finish	Matte Tin (Sn)

<u>Factory Locations</u>	
Wafer Fabrication	CSM AMD SONY UMC
Assembly	ASE, Malaysia
Final Test	ASE, Malaysia

<u>Availability</u>	
Samples:	Yes
Production:	Yes



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Green Package Qualification Stress Tests	#fails/#samples
Preconditioning Jedec Moisture Sensitivity Level 3 with IR reflow at 260 +/- 5°C (Prior to Temperature Cycle)	0/307
Temperature Cycle (-65°C/+150°C, 500 cycles)	0/127 300 cycles 0/77 500 cycles
Autoclave (100 %R.H./2 ATM, 121°C, 96 hrs)	0/277
Solderability	0/20
Assembly Yield	Equivalent to Standard Material set.
Construction Analysis	Complete / Pass

Qualification Date: July 15, 2004

For information on Tin Whiskers, visit the Legerity Green web page at:

<http://www.legerity.com/public.php?p=green>

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